- Reduces Corrosion
- Quick Installation
- Dust Free

CONDUFORM™

Protecting networks and assets

ConduForm™ is a dust free, conductive carbonaceous backfill material that is installed as a liquid and cures as a solid. **ConduForm™** is designed for applications where overburden is shallow or non-existent. It provides superior corrosion and acts as an theft deterrent. It can be poured on exposed rock surfaces to protect conductors and improve grounding where trenching is not possible. With an expected in-service lifetime that is up to 20x the industry standard, electrode corrosion is virtually eliminated. **ConduForm™** offers many advantages:

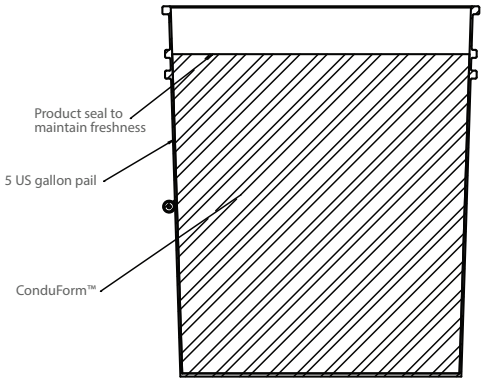
- Pourable – no need to transfer to mixing container
- 99.9% reduction in corrosion of copper
- Environmentally friendly
- Extends the life of the grounding system
- Liquid installation adheres well to native material
- Adheres to bedrock and other bare surfaces
- Cures as a black impermeable solid

ConduForm™ is a low slump, formable product that sets up within 3 hours of installation and forms a strong bond to the native material. It is an environmentally friendly solution that can withstand freeze-thaw cycling, prevent accidental damage and act as an theft deterrent. It is sold in a 5 US gallon container.

Applications

- Grounding on bedrock.
- Rocky shoreline grounding.

Product Specifications



Properties	Typical Value
Appearance	Cured: Black Solid Uncured: Dark Blue Slurry (granular)
Odor	None
Permeability to Water	6.5 x 10^{-6} cm/sec (ASTM D5084)
Resistivity	20 Ω·cm
Electrolytic Corrosion Resistance	
Copper	Eliminated (98 - 100%)
Steel	Eliminated (98 - 100%)
Galvanized Steel	Eliminated (98 – 100%
Freeze-Thaw Withstand	30 years
Environmental Impact	Neutral

Values subject to change.

Updated: 02/11/2020